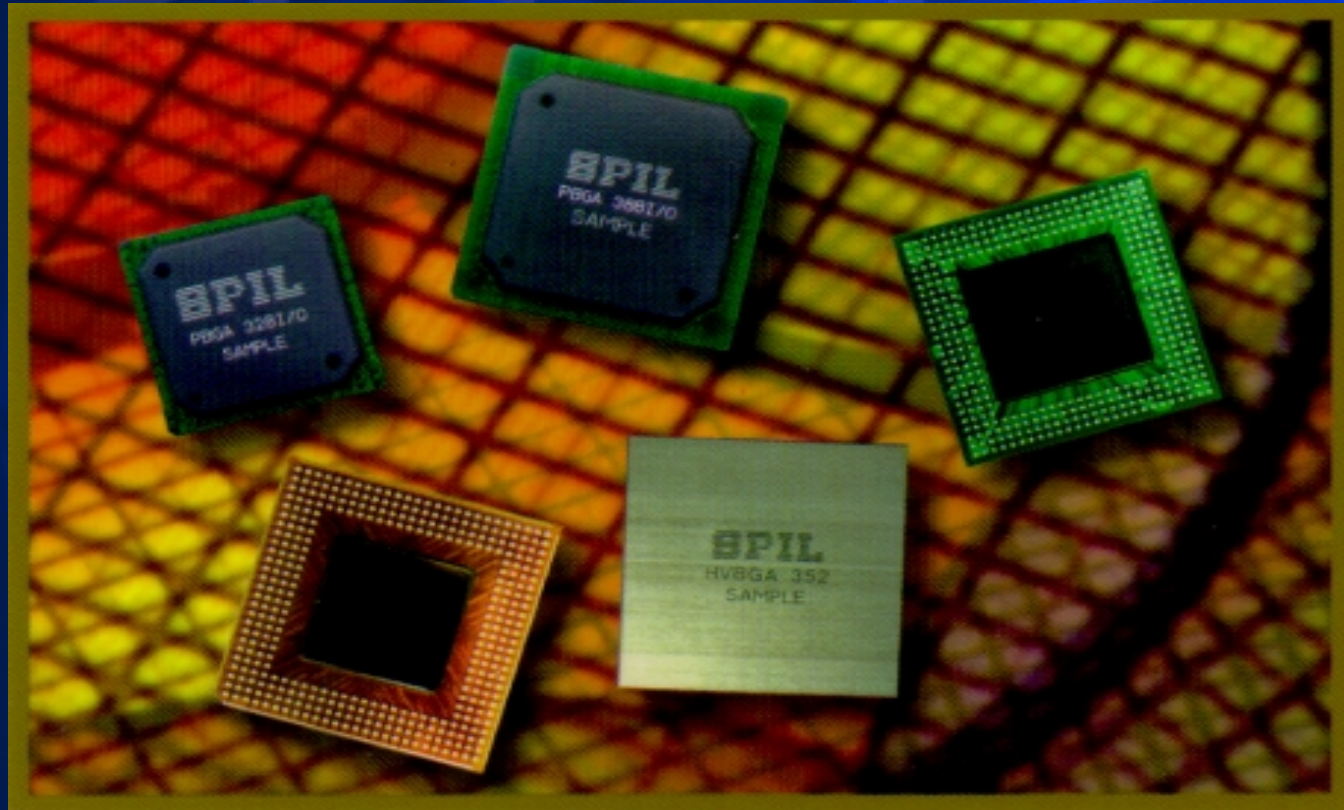


矽品精密工業股份有限公司

Siliconware Precision Industries Co., Ltd.



Investor Conference
August 7, 2002

Bough Lin
Chairman

Safe Harbor Statements



The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things:

- the intensely competitive personal computer, communications, consumer ICs and non-commodity memory semiconductor industries and markets;
- cyclical nature of the semiconductor industry;
- risks associated with international global business activities;
- non-operating losses due to poor financial performance of our investments;
- our dependence on key personnel;
- general economic and political conditions, including those related to the semiconductor and personal computer industries;
- possible disruptions in commercial activities caused by natural and human induced disaster, including terrorist activity and armed conflict;
- fluctuations in foreign currency exchange rates; and
- other risks indentified in our annual report for the year ended December 31, 2001 on Form 20-F filed with the U.S. Securities and Exchange Commission on June 27, 2002.

The words “anticipate,” “believe,” “estimate,” “expect,” “intend,” “plan” and similar expressions, as they relate to us, are intended to identify a number of these forward-looking statements. We undertake no obligation to update or revise any forward-looking statements whether as a result of new information, future events or otherwise. In light of these risks, uncertainties and assumptions, the forward-looking events discussed herein might not occur and our actual results could differ materially from those anticipated in these forward-looking statements.

All financial figures discussed herein are prepared pursuant to ROC GAAP on an unaudited unconsolidated basis. Audited unconsolidated financial figures will be publicly announced upon the completion of our auditing process. The investment gains of our company for the six months ended June 30, 2002 reflect our gains attributable to the first half of 2002 unaudited financial results of several of our investments (the “Investees”) which are evaluated under the equity method with the exception of gains and losses attributable to ChipMOS, herein excluded pursuant to the SFC’s grant of a one year accounting deferment. The unaudited unconsolidated financial data for our company for the six months ended June 30, 2002 are not necessarily indicative of the results that may be expected for any period thereafter.

2Q 02 Income Statement YoY Comparison



Amount: NT\$Million	2Q 2002		2Q 2001		YoY
	Actual	%	Actual	%	Chg %
Net Sales	5,398	100.0	3,480	100.0	55.1
Cost of Goods Sold	(4,853)	-89.9	(3,323)	-95.5	46.0
Gross Margin	545	10.1	157	4.5	246.6
Operating Expense	(355)	-6.6	(363)	-10.4	-2.2
Operating Income	190	3.5	(206)	-5.9	—
Non-operating Income	230	4.3	163	4.7	40.9
Non-operating Expense	(242)	-4.5	(472)	-13.6	-48.8
Income before Tax	178	3.3	(515)	-14.8	—
Income Tax Credit (Expense)	7	0.1	300	8.6	-97.9
Net Income	185	3.4	(215)	-6.2	—

2Q 02 Income Statement QoQ Comparison



Amount: NT\$Million	2Q 2002		1Q 2002		QoQ
	Actual	%	Actual	%	Chg %
Net Sales	5,398	100.0	5,252	100.0	2.8
Cost of Goods Sold	(4,853)	-89.9	(4,699)	-89.5	3.3
Gross Margin	545	10.1	553	10.5	-1.3
Operating Expense	(355)	-6.6	(370)	-7.0	-4.0
Operating Income	190	3.5	183	3.5	4.1
Non-operating Income	230	4.3	155	3.0	48.8
Non-operating Expense	(242)	-4.5	(225)	-4.3	7.7
Income before Tax	178	3.3	113	2.2	58.2
Income Tax Credit (Expense)	7	0.1	43	0.8	-85.0
Net Income	185	3.4	156	3.0	18.8

1H 02 Income Statement

YoY Comparison



	1H 2002		1H 2001		YoY
	Actual	%	Actual	%	Chg %
Amount: NT\$Million					
Net Sales	10,650	100.0	8,038	100.0	32.5
Cost of Goods Sold	(9,552)	-89.7	(7,242)	-90.1	31.9
Gross Margin	1,098	10.3	796	9.9	38.0
Operating Expense	(725)	-6.8	(715)	-8.9	1.4
Operating Income	373	3.5	81	1.0	359.4
Non-operating Income	385	3.6	314	3.9	22.8
Non-operating Expense	(467)	-4.4	(691)	-8.6	-32.4
Income before Tax	291	2.7	(296)	-3.7	—
Income Tax Credit (Expense)	50	0.5	465	5.8	-89.4
Net Income	341	3.2	169	2.1	101.3
Diluted Earnings Per Ordinary Shares	NT\$ 0.19		NT\$ 0.09		
Diluted Earnings Per ADS	US\$ 0.028		US\$ 0.013		
Weighted average outstanding shares ('K)	1,825,746		1,885,174		

Balance Sheet Highlight- June 30, 2002



June 30,2002

Amount: NT\$Million

Actual %

Cash and Cash Equivalents	7,213	16
Long-term Investments	7,991	17
Fixed Assets	23,359	50
Total Assets	46,566	100
LT Debt	14,322	31
Shareholder Equity	26,328	57
Depreciation	2,244	
Capital Expenditure	3,221	

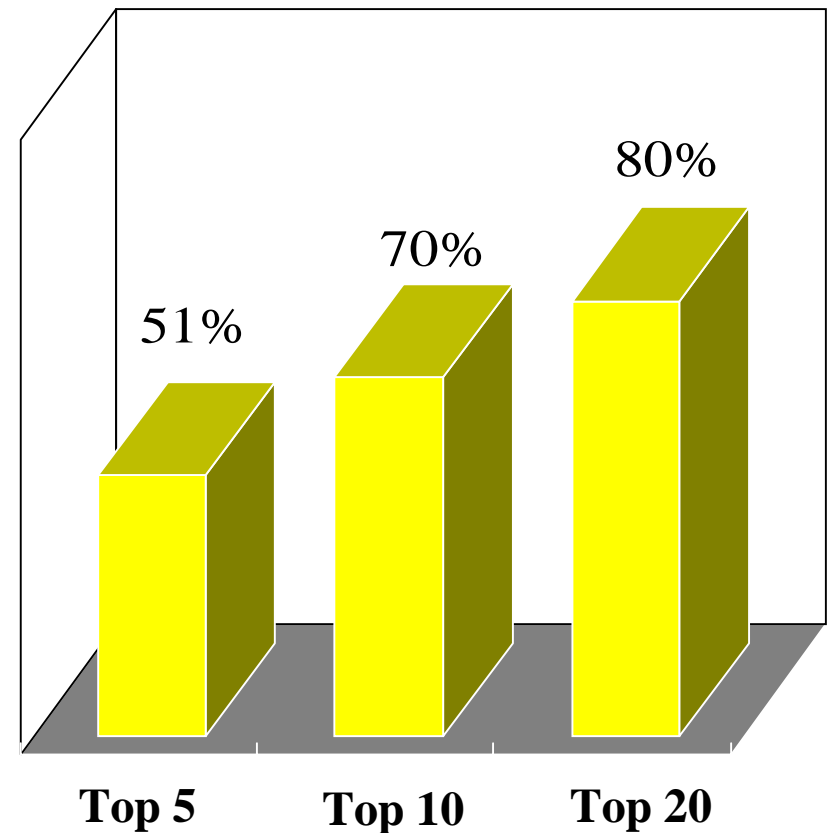
Top 20 customers



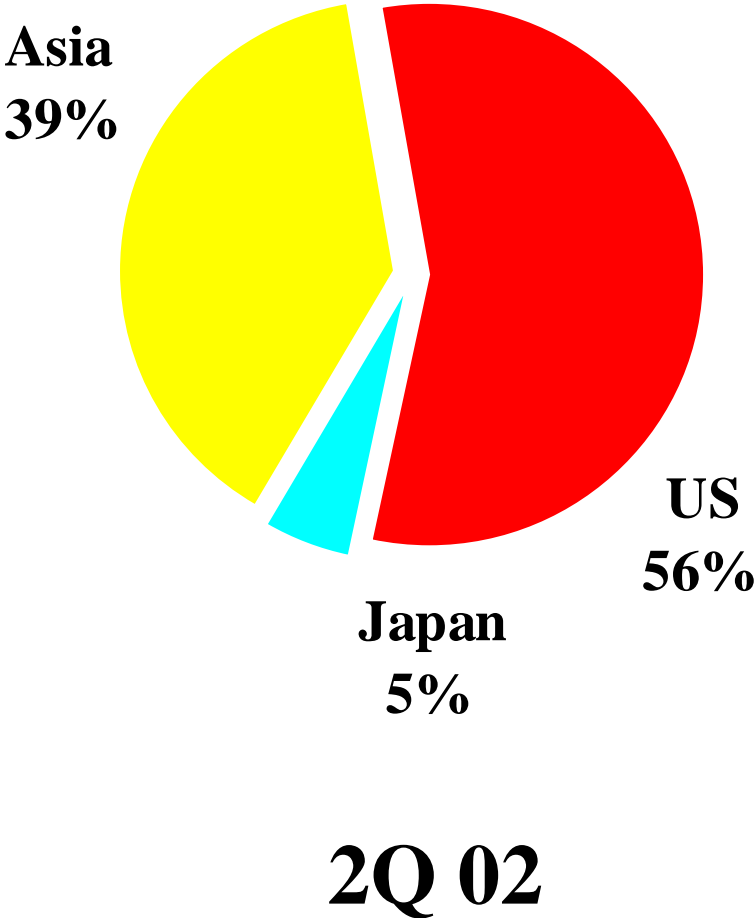
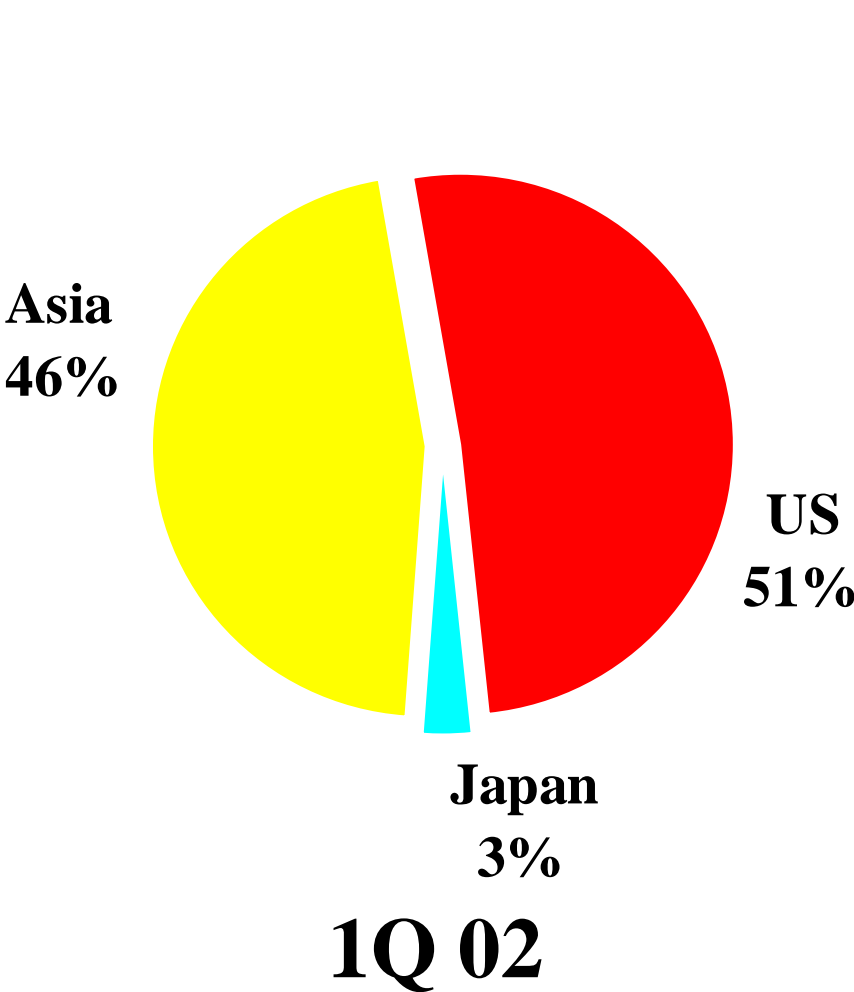
Ali
AMIC
ATI
Broadcom
Cirrus Logic
EliteMT
Faraday
Genesis
LSI Logic
Marvell

MXIC
Mediatek
nVidia
Realtek
Ricoh
Sandisk
Vanguard
Via
Winbond
Xilinx

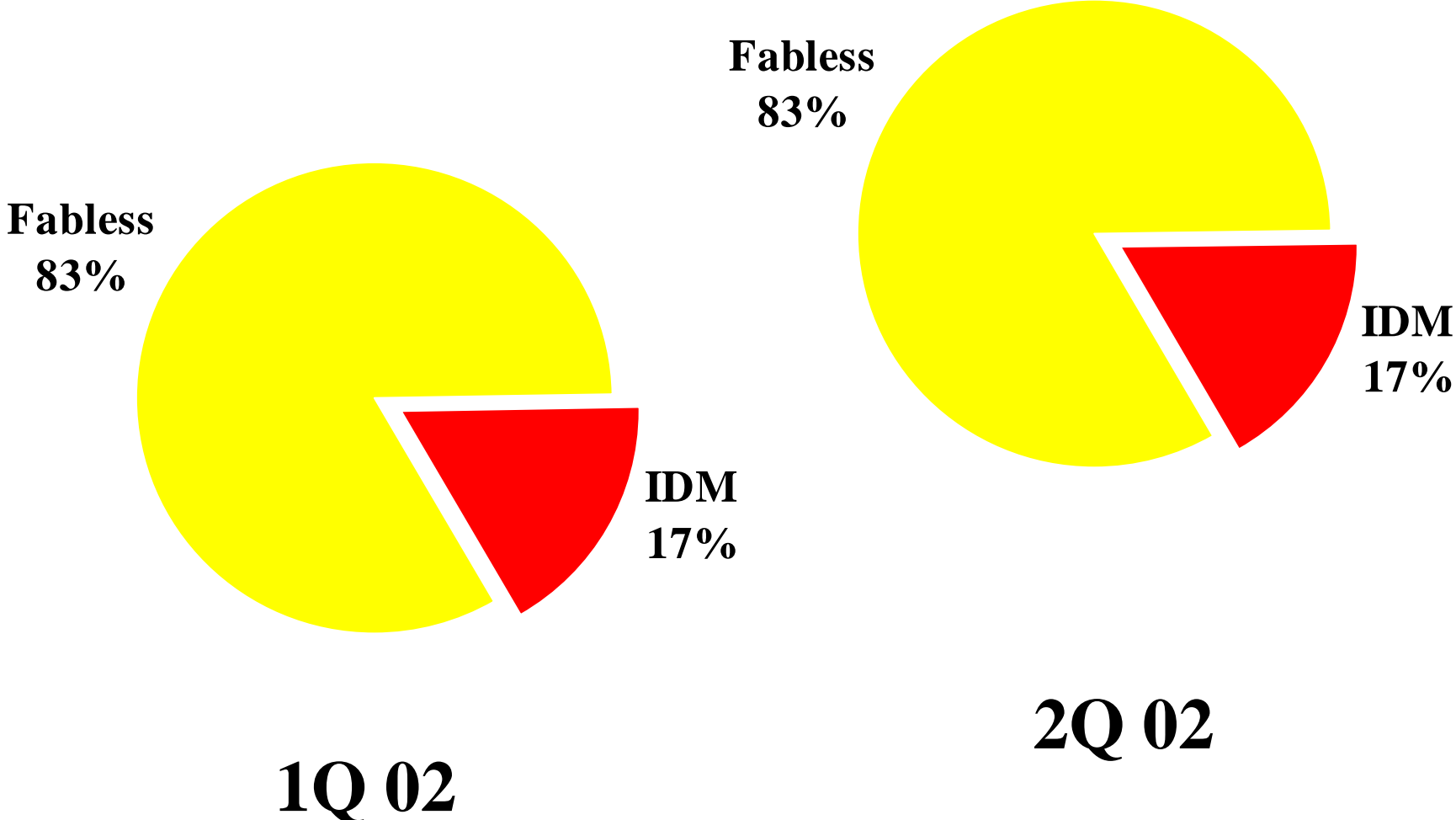
Customers Concentration



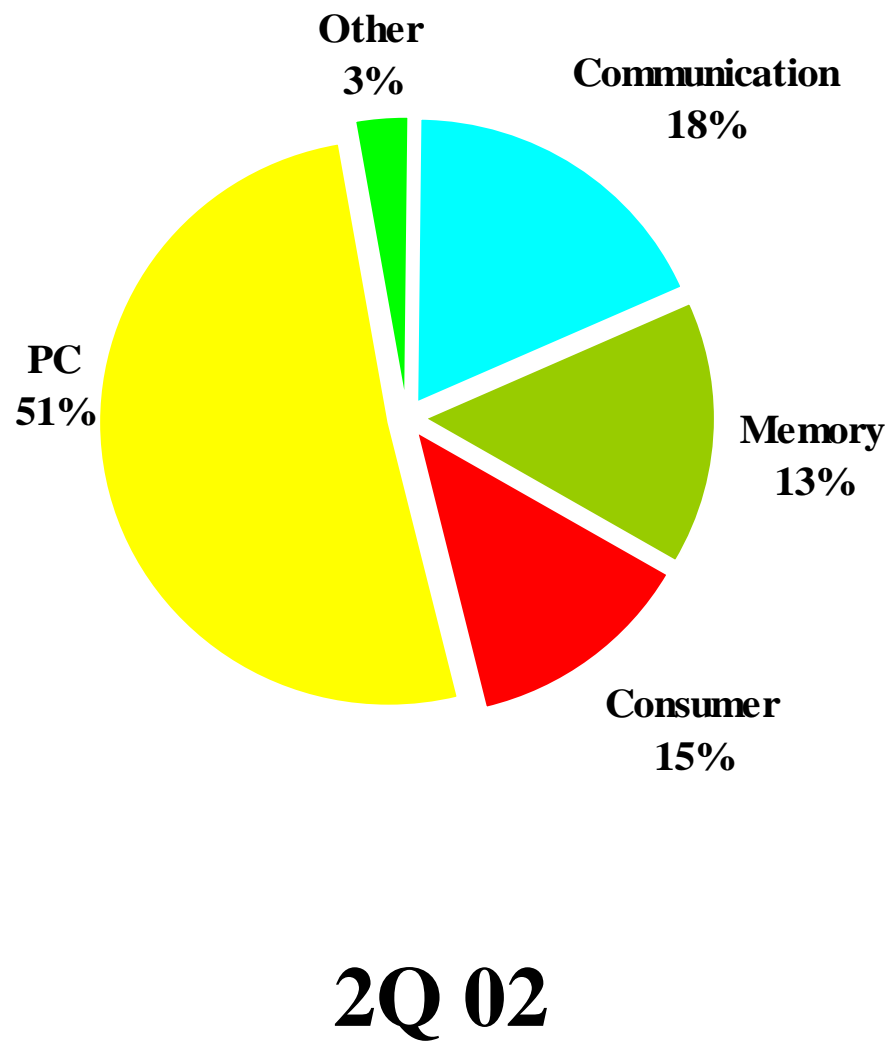
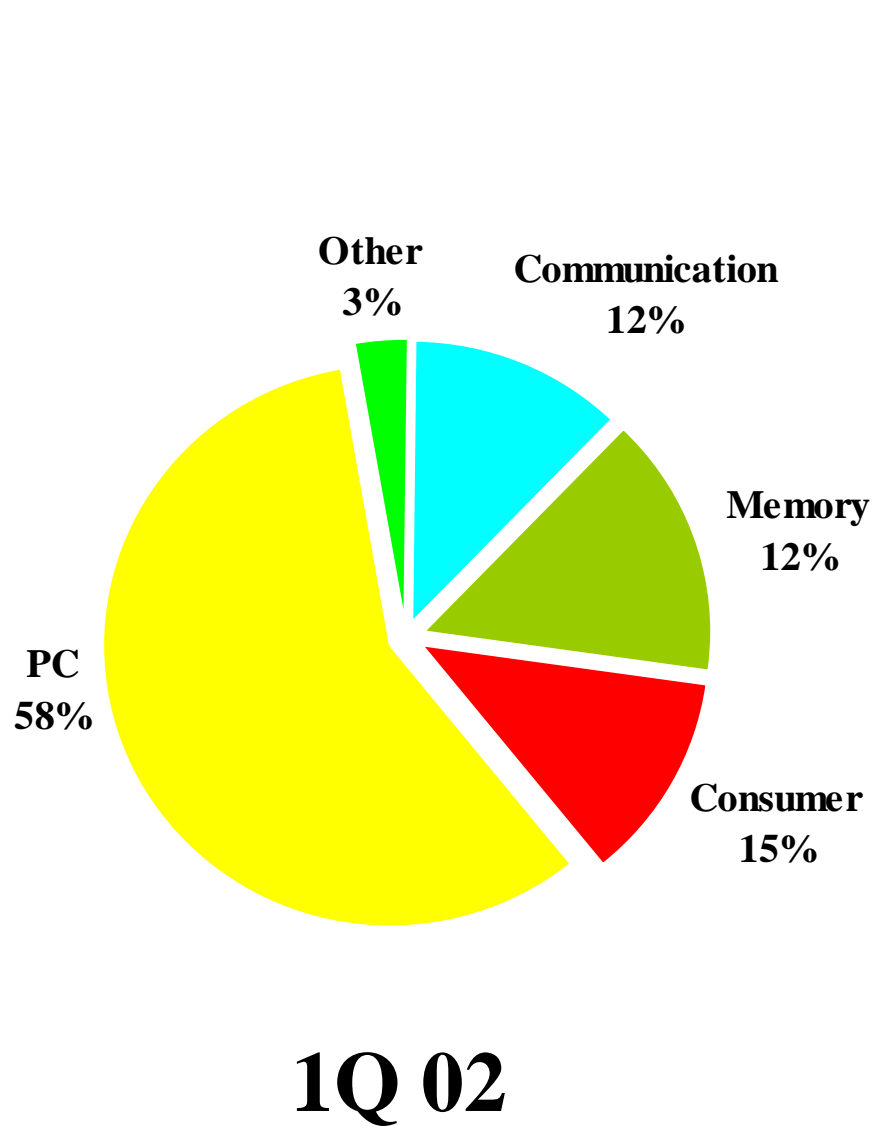
Sales Breakdown by Geography



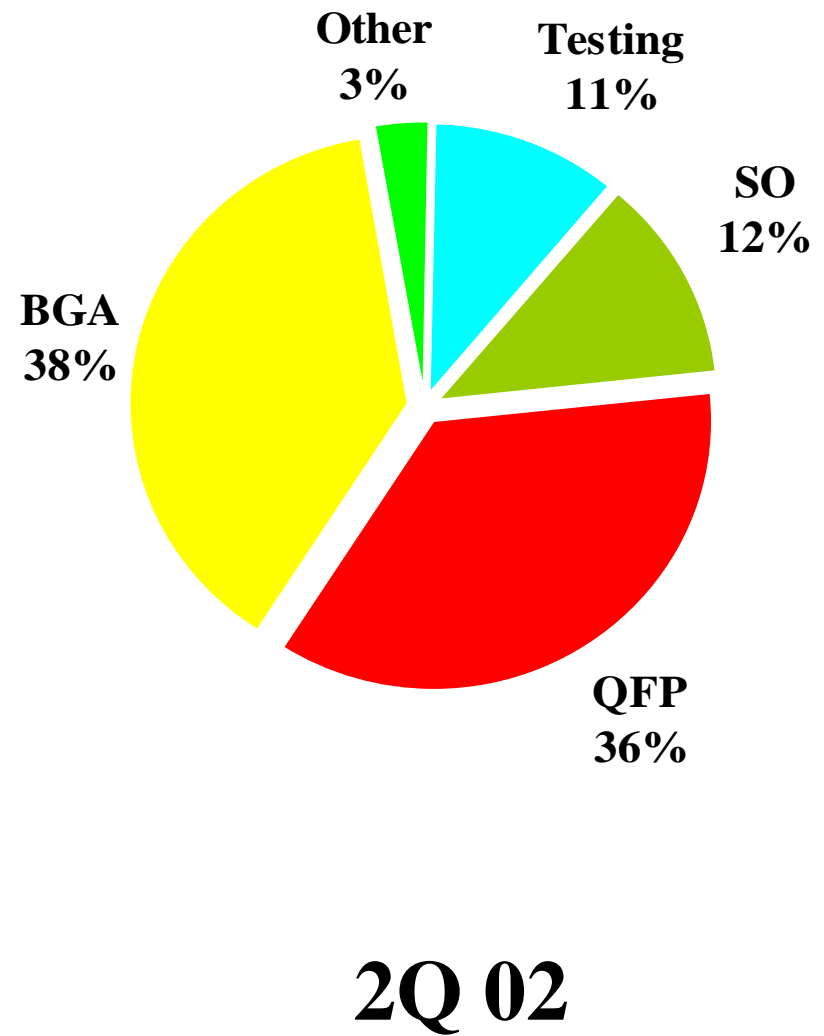
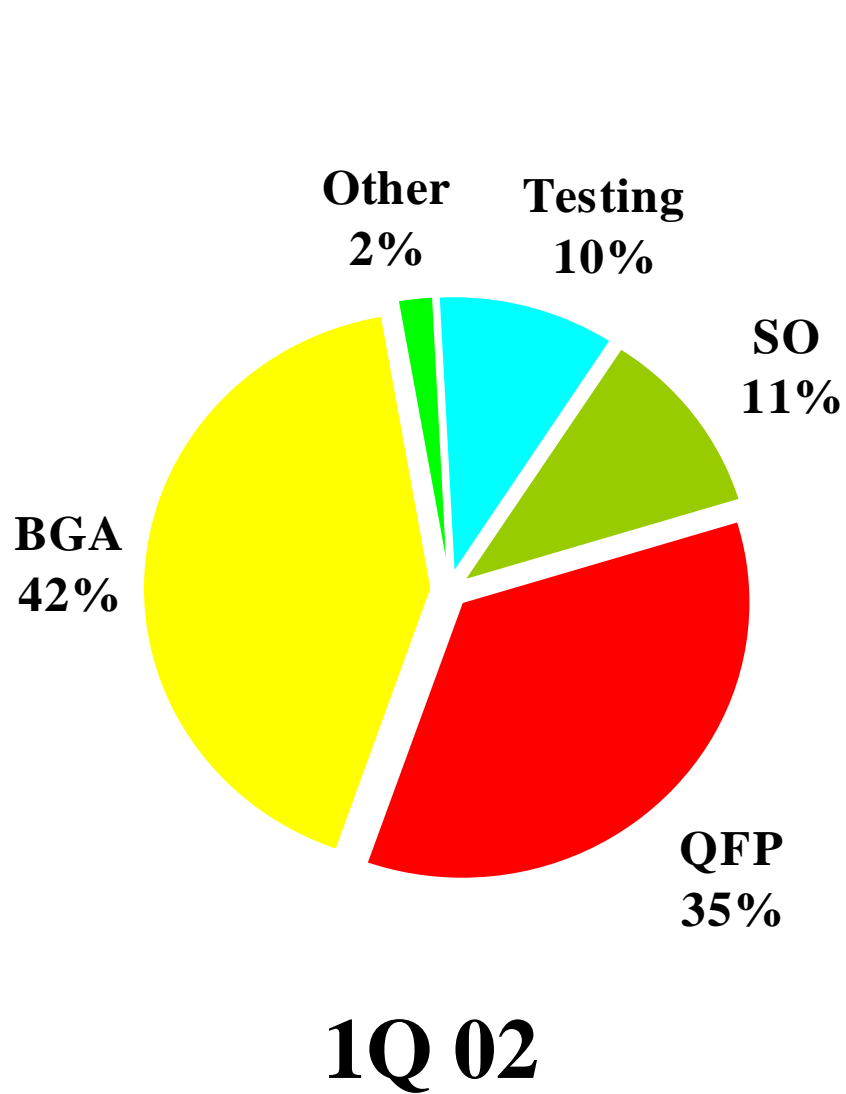
Sales Breakdown by Customer



Sales Breakdown by Application



Sales Breakdown by Product Type



Capacity-Wirebonder, Tester, Headcount



Item \ Period	2Q 01	3Q 01	4Q 01	1Q 02	2Q 02
Wirebonder	1,868	1,888	2,085	2,225	2,325
Tester	163	165	171	186	190
Headcount	6,019	6,064	6,610	7,300	7,980

Advanced Packaging in Production



- 12" Wafer Bumping
- 12" Wafer Flip Chip Assembly
- Wafer Level CSP(WLCSP)
- Multi-Package BGA
- Story Stacked Die CSP Package
- 48 um in-line Fine Pitch Wire Bonding

Advanced Packaging in Development

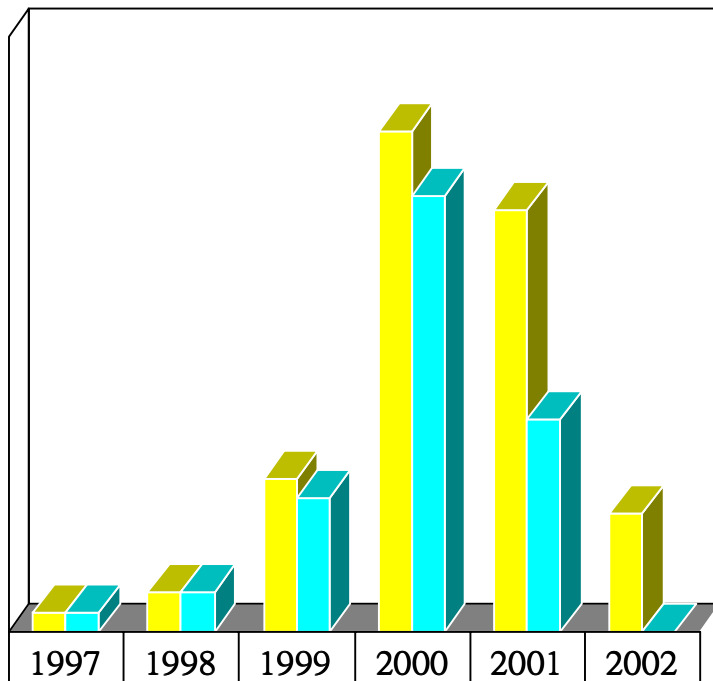


- Multi-Package Flip Chip BGA
- Lead-Free Flip Chip Assembly
- High-Lead Flip Chip Assembly
- Thin Wafer(4 mil) Assembly Technology
- 45 um in-line Fine Pitch Wire Bonding

Patent Filing & Granted

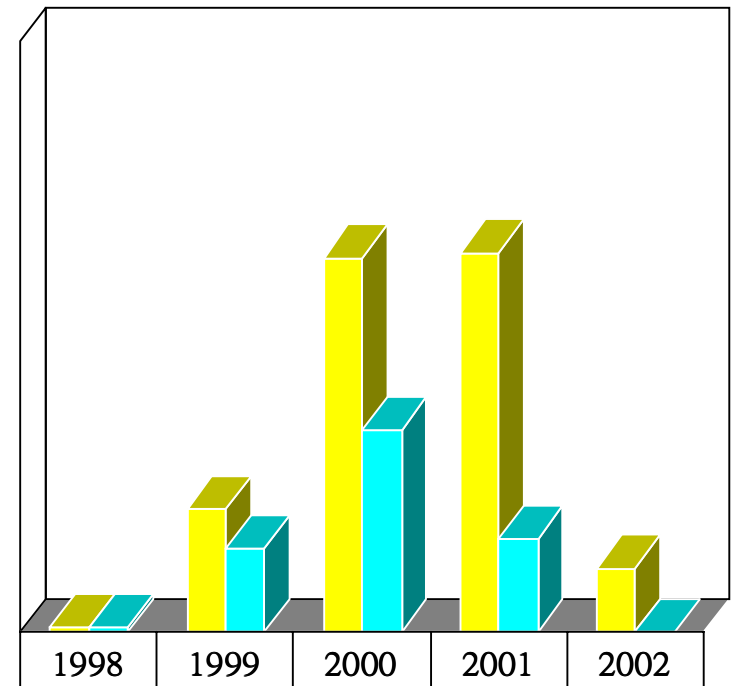


Taiwan



■ Filing	4	8	31	101	85	24
■ Granted	4	8	27	88	43	0

U S A



■ Filing	1	25	76	77	13
■ Granted	1	17	41	19	0

SPIL & Affiliates' Sales Revenue



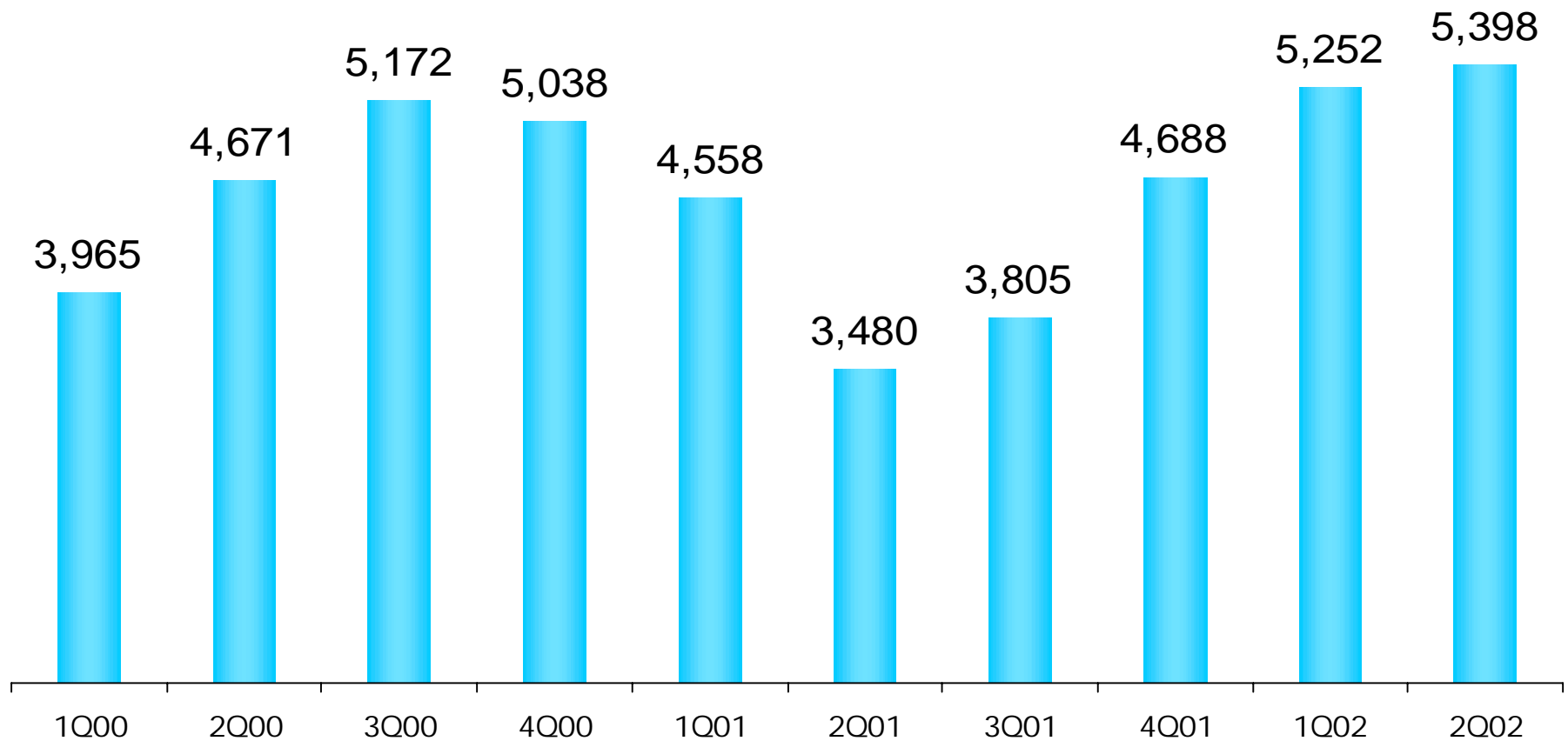
Amount: NT\$Million

Investees	Business	Ownership %	Revenue			
			2001		1H 2002	
			Assembly	Test	Assembly	Test
SPIL	IC Assembly & Test	—	14,801	1,729	9,575	1,075
ChipMOS Tech.	DRAM & TCP Assembly & Test	29	1,742	3,505	1,074	1,908
SIGURD	PDIP/SO Assembly & Test	34	415	406	209	328
ThaiLin	Memory Test	9	—	718	—	428
Ucomm	RF Test	43	—	58	—	69
ARTEST	Mixed Signal & RF Test	31	—	565	—	105
Total			16,958	6,981	10,858	3,913
Phoenix Precision	IC Substrates	17	2,073	—	1,266	—

SPIL Quarterly Revenue



Amount:NT\$ Million



<http://www.spil.com.tw>